

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 6, line 11, with the following rewritten paragraph:

The lower diffusion block 90 is adhered to the bottom of the intermediate diffusion block 80. A diffusion region 92 may be formed on the lower diffusion block 90 to uniformly distribute the second reactive gas supplied through the second distributing hole 84. The diffusion region is rough, i.e., a plurality of convex portions (凸) 95 and a plurality of concave portions (凹) 96 are formed in the diffusion region. A plurality of second spray holes 94 are respectively formed in the concave portions (凹) 96 and used to spray the second reactive gas supplied from the second distributing hole 84 on the wafer W. Also, a plurality of first spray holes 93 are respectively formed in the convex portions (凸) 95 and respectively connected to the first distributing holes 83. That is, the first spray holes 93 penetrate the convex portions (凸) 95, and the second spray holes 94 penetrate the concave portions (凹) 96.